

Mixed-Signals Integrated Circuit Testing

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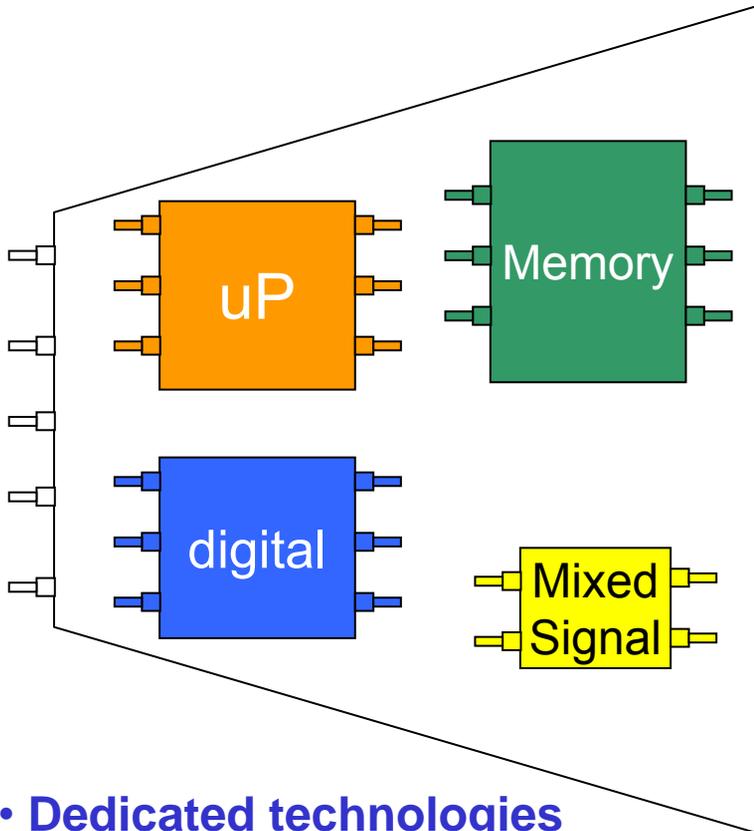
Montpellier, 27th March 2007

Outline

- 1 Introduction
- 2 Analog versus digital testing
- 3 Structural and functional testing
- 4 Analogue DFT/BIST techniques
- 5 Computer-Aided Test (CAT) techniques
- 6 Conclusions

1 Introduction

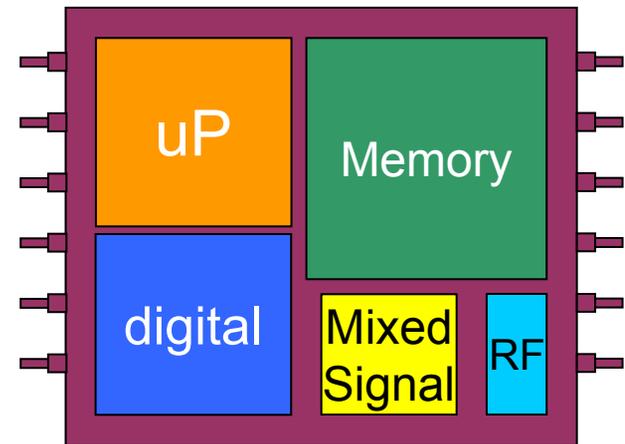
System-On-Board (SOB)



- Dedicated technologies
- Pre-tested ICs
- Board-Level Test



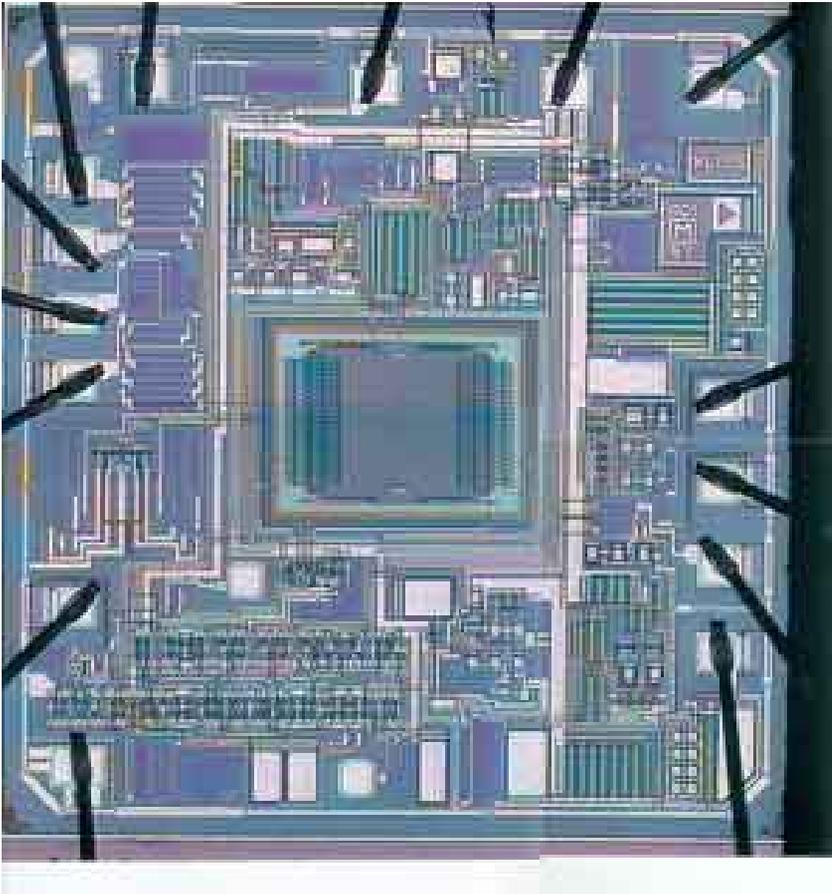
System-On-Chip (SOC)



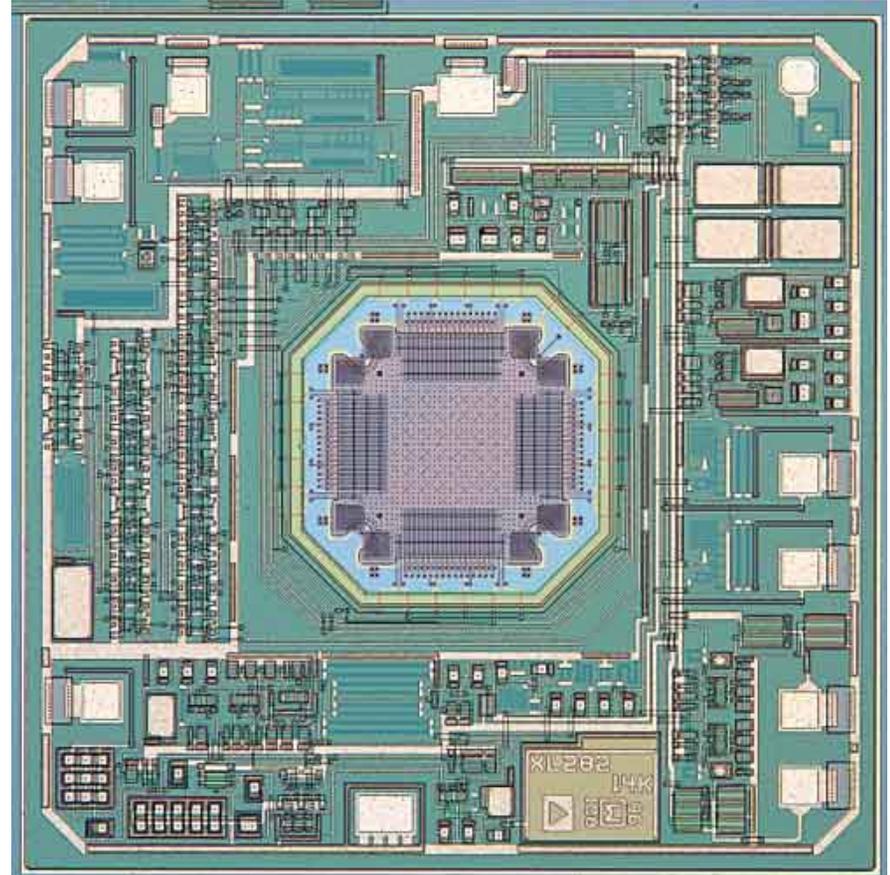
- Mixed technologies on the same chip
- Pre-designed blocks (not tested)
- Core and IC level test data

1 Introduction

→ Accelerometer examples :



Self-testable one axis accelerometer



Self-testable two axis accelerometer

1 *Introduction*

→ Motivation of mixed-signals testing :

- ❑ Growth in mixed-signals ICs : efforts to combine analog, digital and memories to provide SoC solutions
- ❑ Driven by communication and consumer markets
- ❑ In mixed-signal systems, over 90% is often digital but 90% test cost can be analogue
- ❑ Communications and biomedical applications are demanding new SoC and SiP devices
- ❑ Testing mixed-signals devices is very different from digital testing

1 *Introduction*

→ What are we testing for ? **Physical defects**

❑ Cause : process disturbances

- Local (silicon defects, photolithography spots ...)
- Global (mask misalignment, bad micromachining ...)

❑ Fault types :

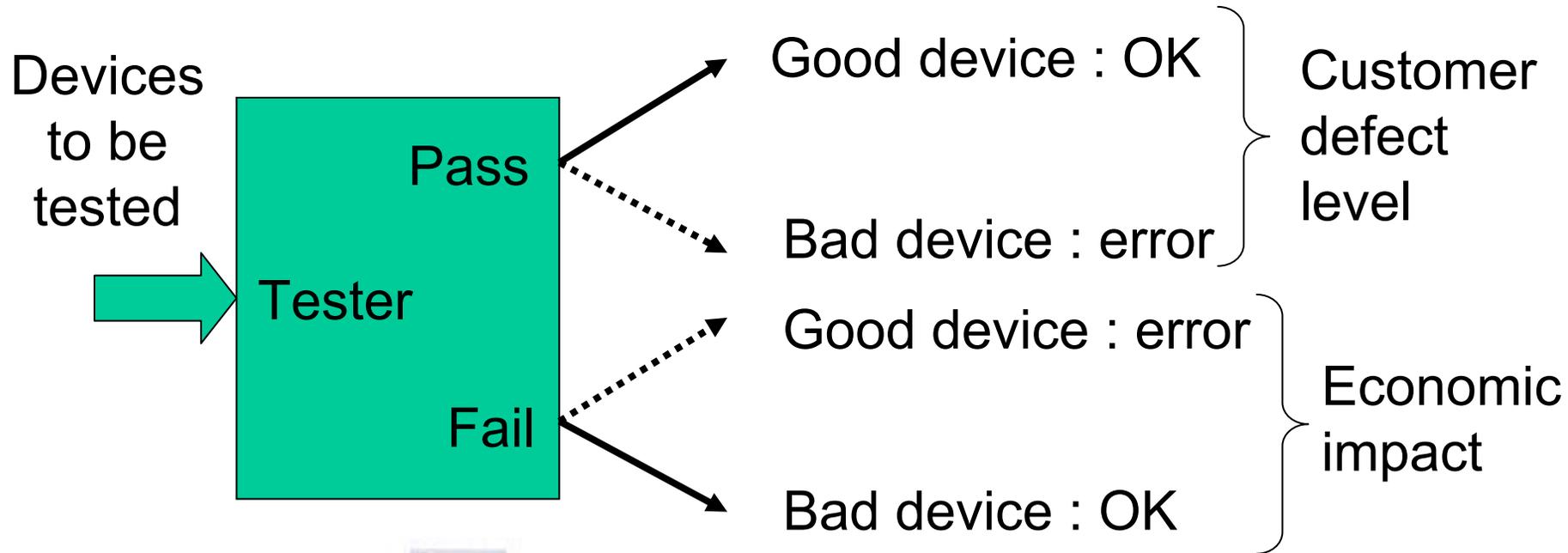
- Structural faults : opens, shorts, ...
- Parametric faults : variations in device parameters
have a more important impact on analogue testing

❑ Failures :

- Hard (incorrect performance, large performance error)
- Soft (marginal out-of-spec performance)

1 Introduction

→ Production test: quality and economic impact



2 Analog versus digital testing

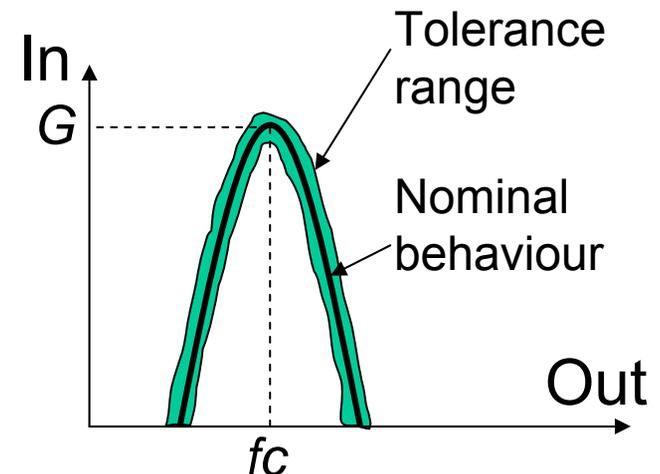
□ Digital Testing :

- ♠ Discrete binary values (0/1)
- ♠ Truth tables (exact)
- ♠ Simple parametric testing (e.g. current consumption at wafer level)
- ♠ Fault-based (structural) or functional testing based on exact logic behaviour at chip and package levels

X1	X2	X3	X4	Y
0	0	0	0	1
0	0	0	1	0
0	0	1	0	1

□ Analog Testing :

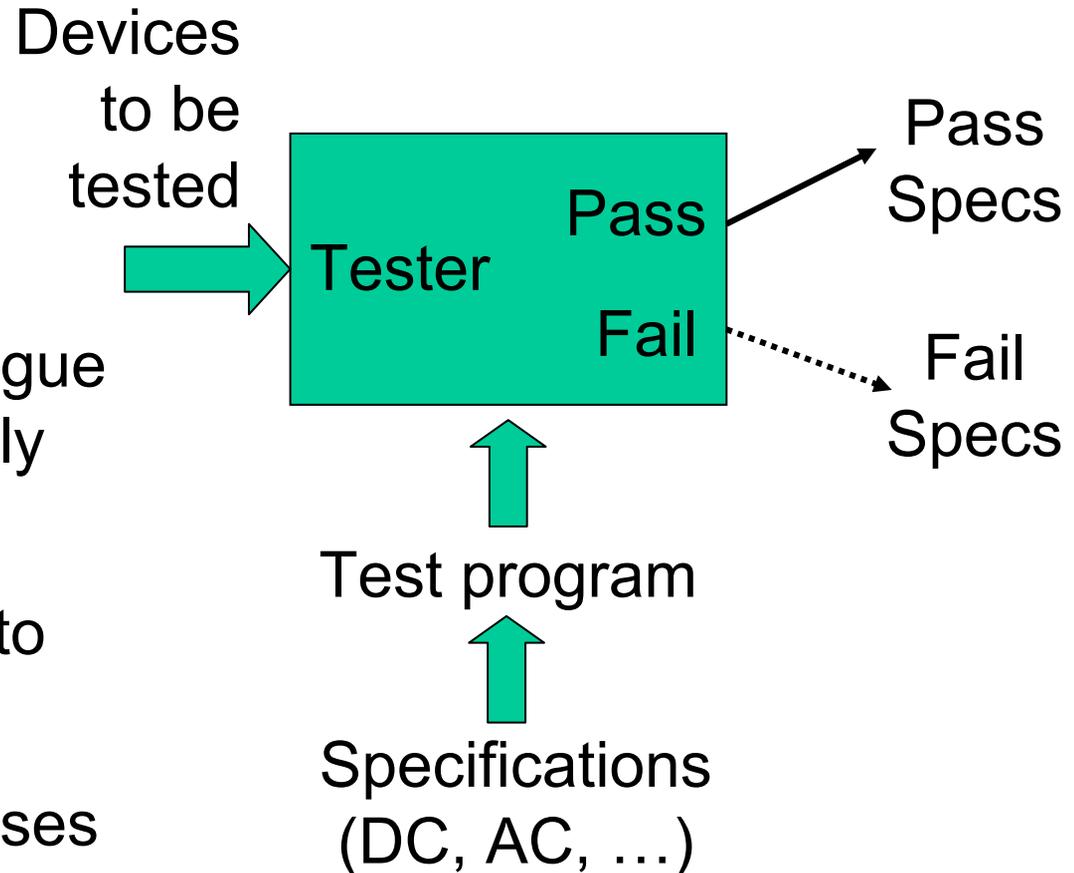
- ♠ Continuous values
- ♠ Differential equations (approx)
- ♠ Specification-based testing considering acceptance ranges for design parameters



3 Structural and functional testing

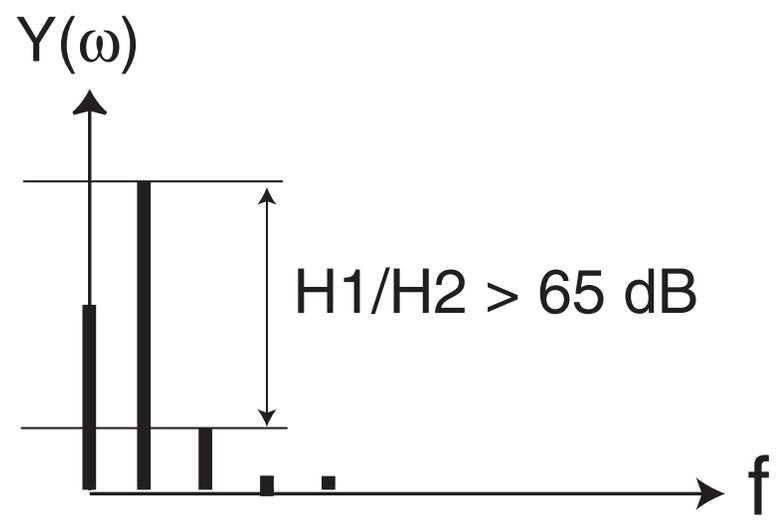
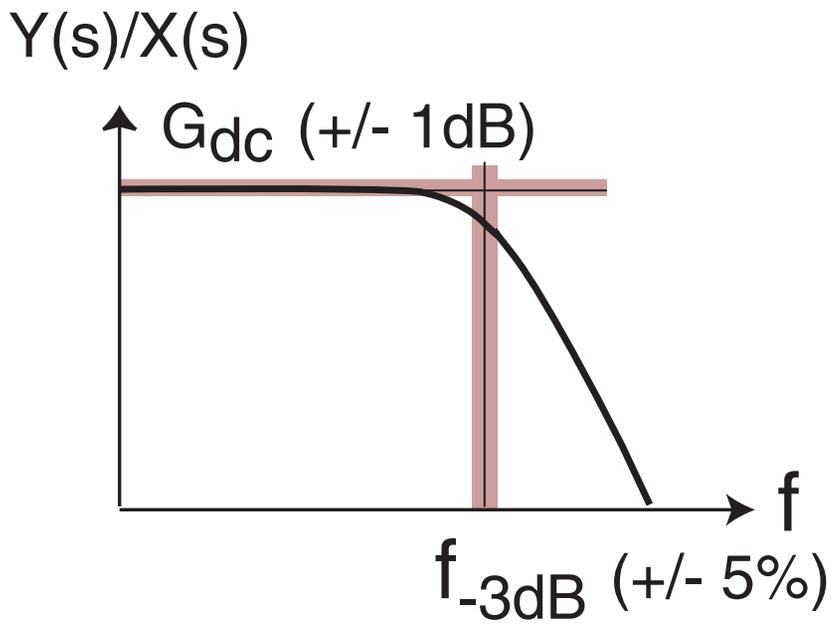
→ Functional testing :

- Test matches the functionality
- Simple test vector generation
- Typically used for analogue devices but leads to costly test equipment
- Lengthy test time due to redundant tests
- Test complexity increases exponentially with device size for digital circuits



3 Structural and functional testing

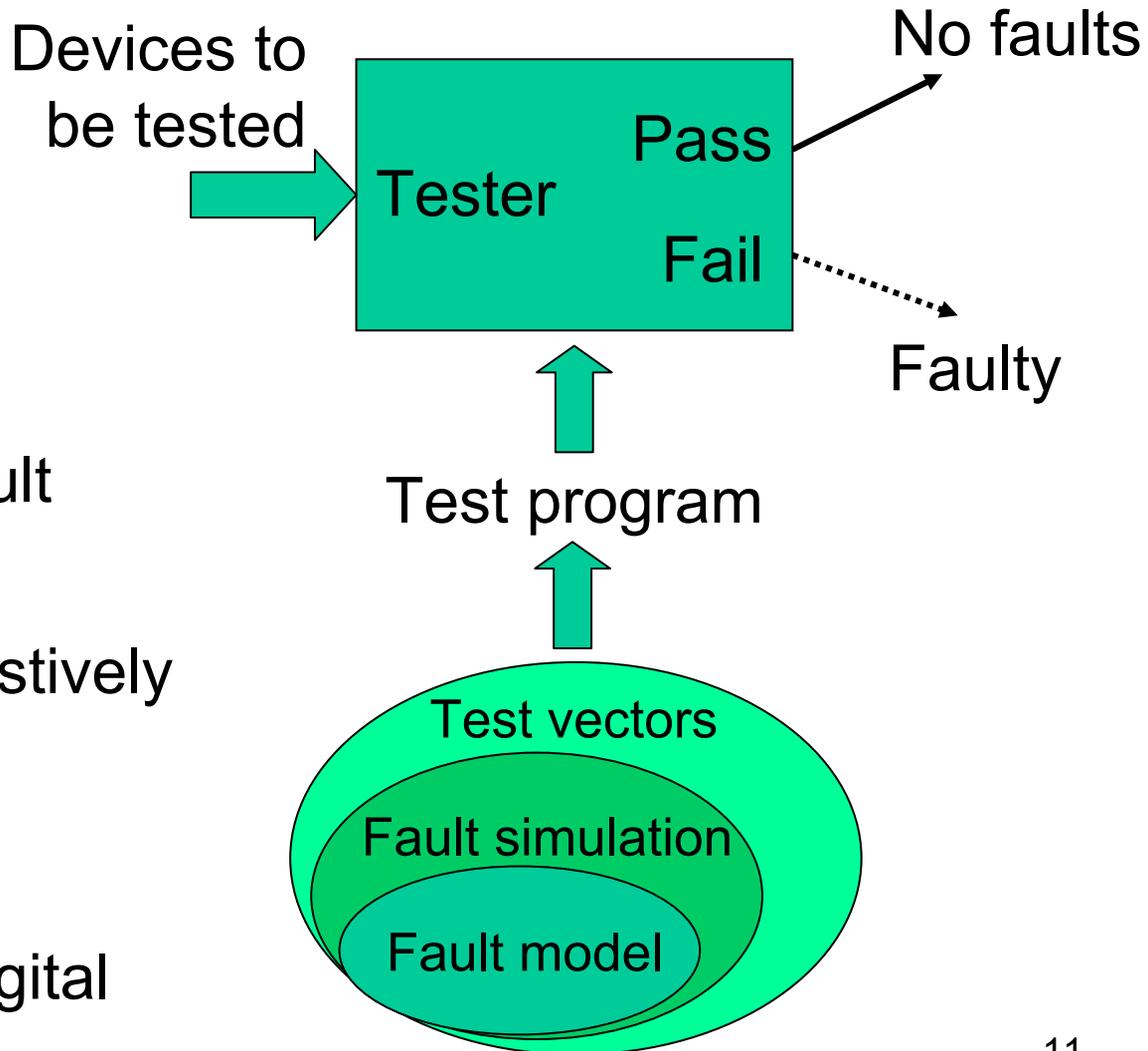
→ Examples of specification-based tests



3 Structural and functional testing

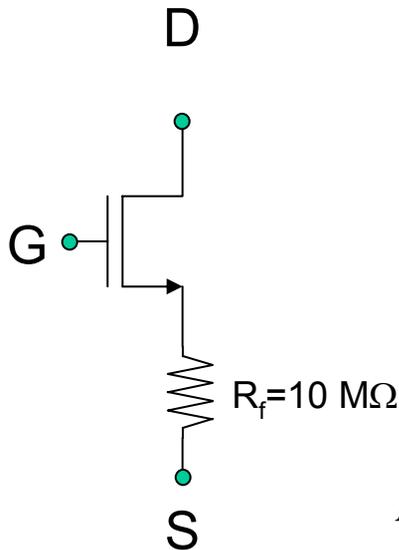
→ Structural testing :

- Tests targeting structural defects
- Based on the use of fault models
- CAD tools for test generation (ATPG, fault simulation)
- Does not test exhaustively for functionality
- Less expensive test
- Typically used for digital devices

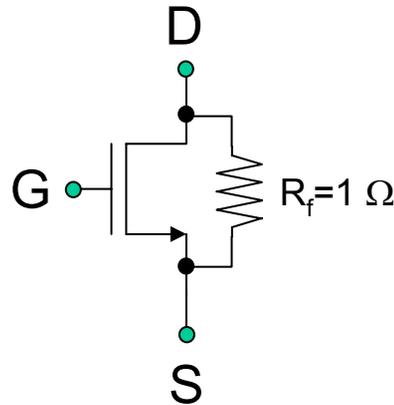


3 Structural and functional testing

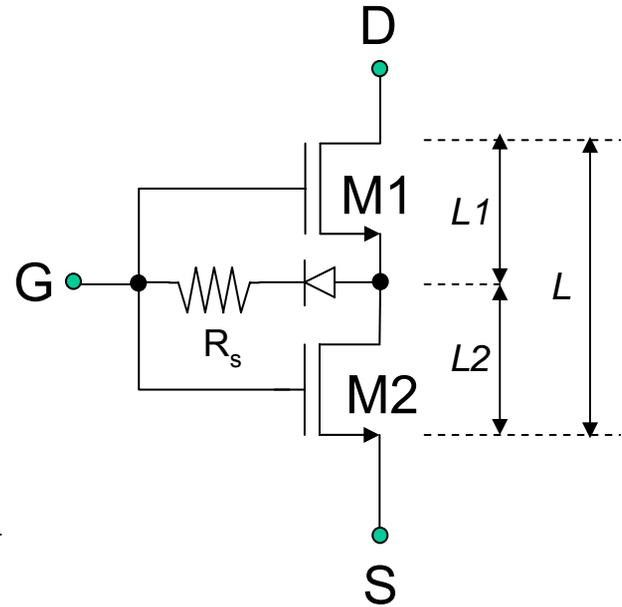
→ Modeling of catastrophic faults :
examples at circuit level



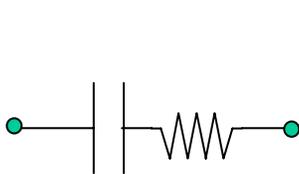
MOS Source open



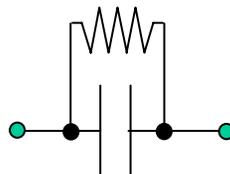
MOS Drain-Source short



MOS Gate-Oxide short



Capacitor open



Capacitor short

Hierarchical faster fault simulation requires the use of higher level (behavioural) fault models

4 *Analog DFT/BIST techniques*

→ *Standards for IC testing:*

- ❑ 1149.1 Standard digital boundary-scan test (1990)
 - Aims to facilitate observability and controllability of IC signals, in particular transforming very difficult PCB testing problems into well structured ones easily solved by software
- ❑ 1149.4 Standard Mixed-Signal test bus to be used at device, sub-assembly and system levels (1999)
 - Aims to increase the observability and controllability of mixed-signal designs and support MS-BIST structures
- ❑ P1500 Standard test method for embedded cores (working group)
 - Focused on Standardized Core Test Language (CTL) and configurable & scalable test wrapper for easy core access

4 *Analog DFT/BIST techniques*

→ *BIST Principle*

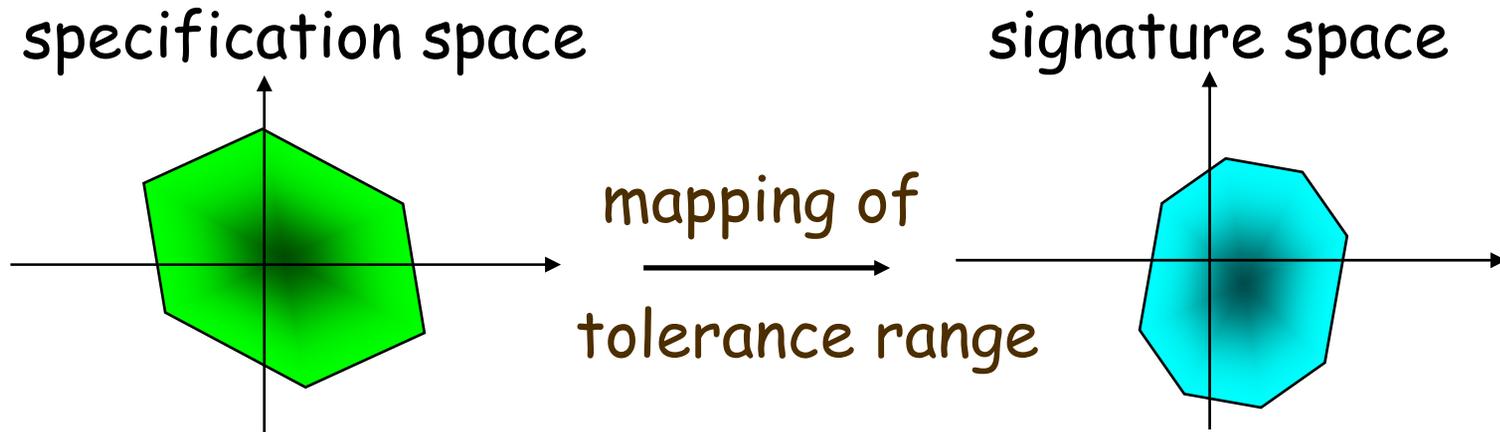
- On-chip analogue test signal generation
- On-chip analogue test response analysis

→ *Current trends*

- Enabling each element in an analog chain to be tested independently
- Reducing requirement for complex functional tests
- Improving test reuse
- Exploring the use of digital techniques (as much as possible) for stimulus generation and measurement

4 Analog DFT/BIST techniques

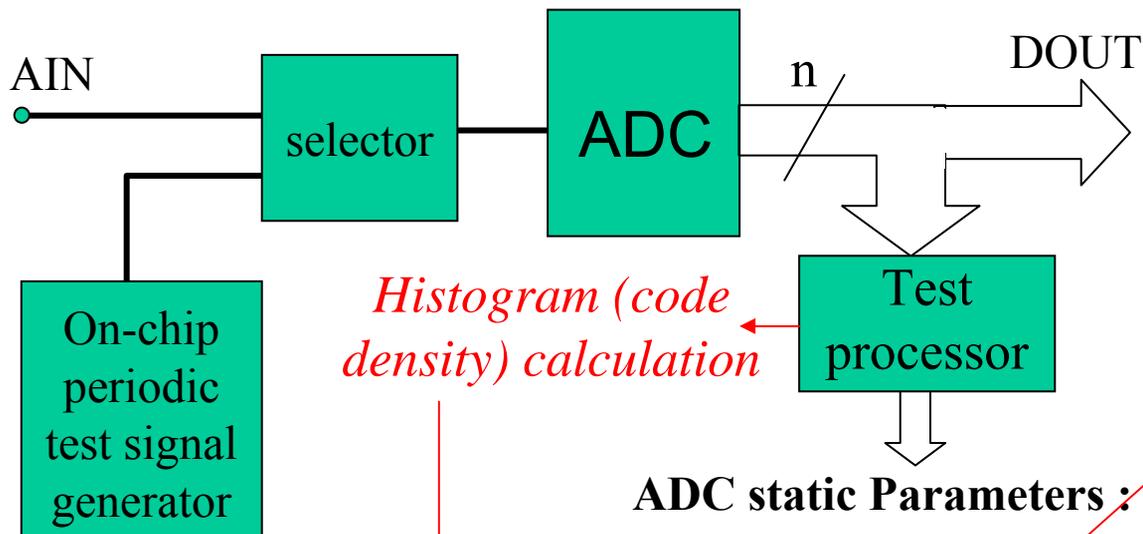
→ *BIST* relies on accurate mapping of tolerance range



- Perfect mapping may not be possible
 - Objective: minimize misclassification

4 Analog DFT/BIST techniques

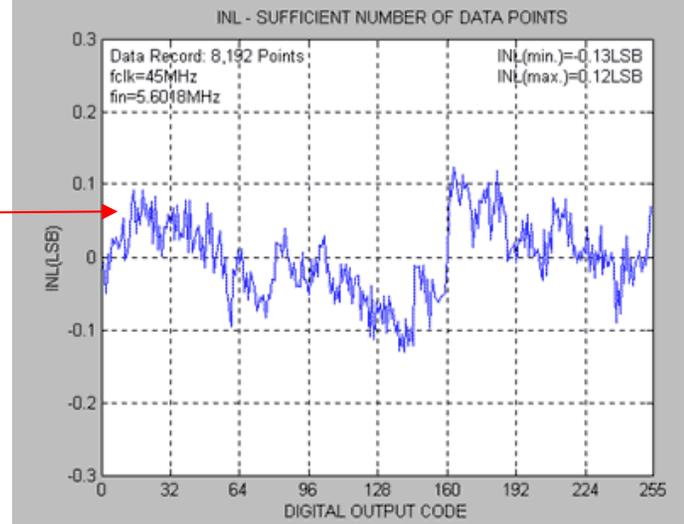
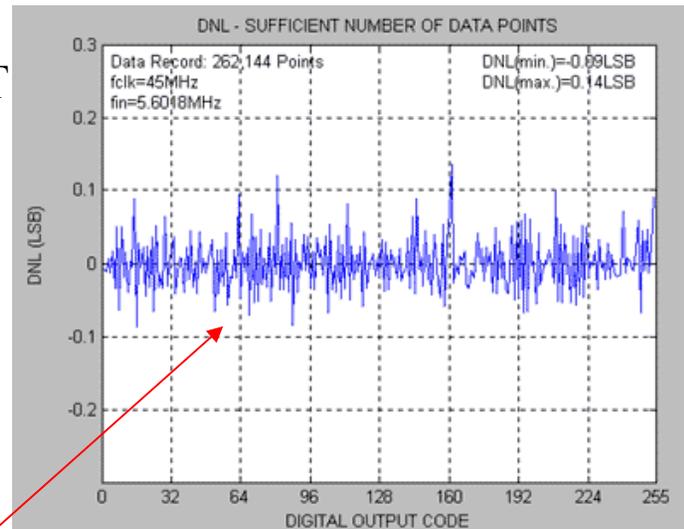
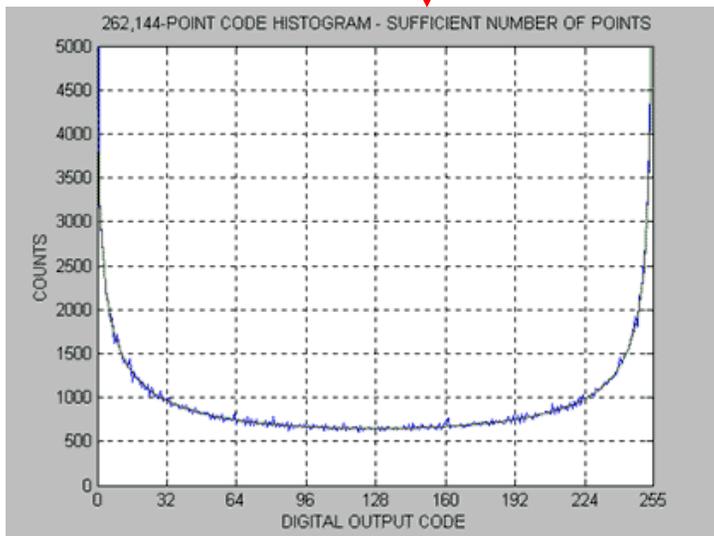
→ Histogram (code density) BIST for ADCs :



ADC static Parameters :

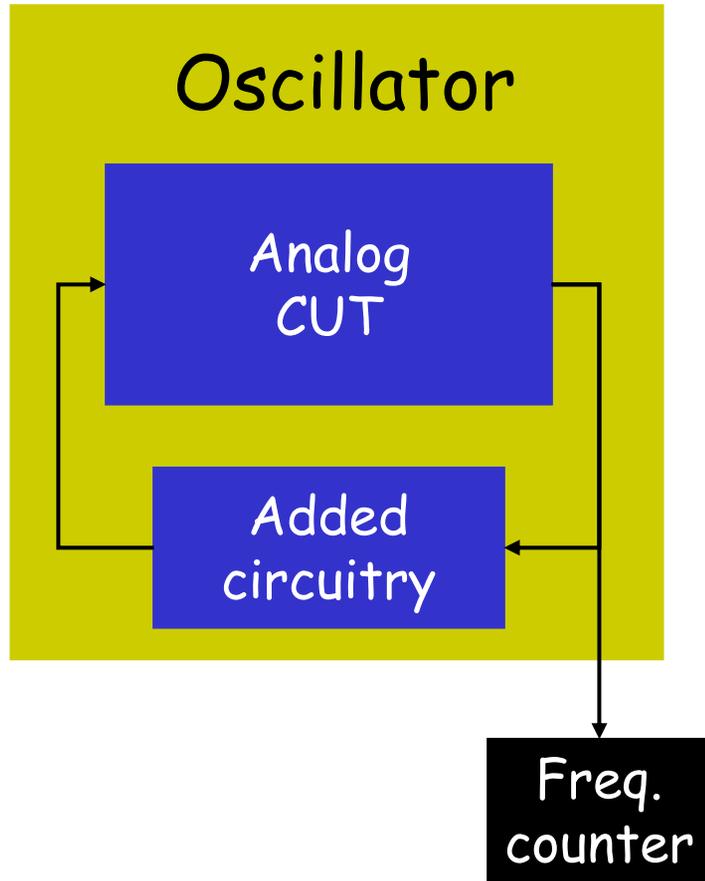
Offset,
Gain
DNL,
INL

Obtained by comparison with ideal histogram



4 Analog DFT/BIST techniques

→ Oscillation BIST



- Analog CUT plus added circuitry become an oscillator in test mode
 - Oscillation induced through positive feedback
- Defects cause deviations in
 - Oscillation frequency
 - Oscillation amplitude

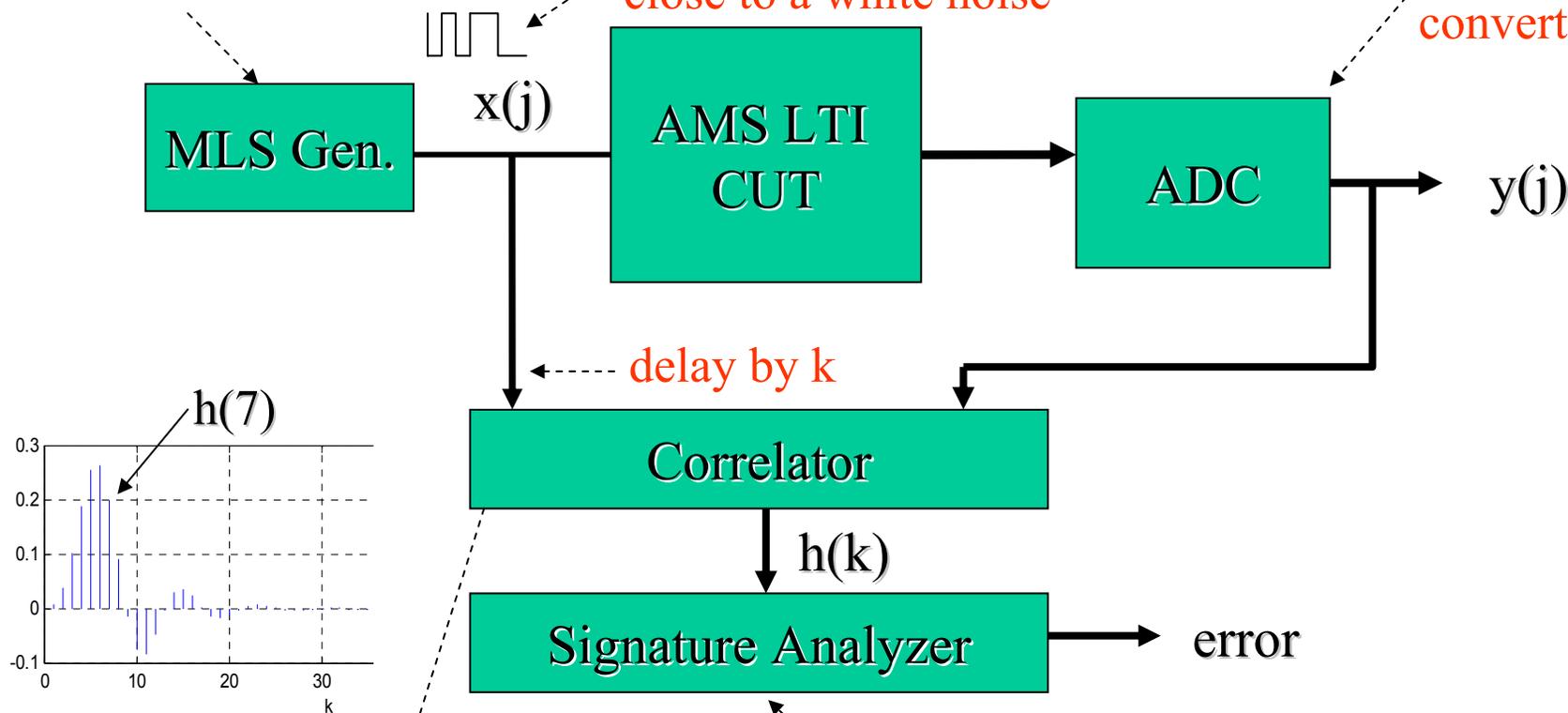
4 Analog DFT/BIST techniques

→ Pseudo-random testing of LTI circuits :

pseudo-random test vector generator (BILBO register)

signal power spectrum close to a white noise

self-testable converter



$$\phi_{xy}(k) = \frac{1}{N} \sum_{j=0}^{N-1} x(j-k) y(j)$$

Mapping the physical parameter space to the IR space; selection of optimal impulse response samples

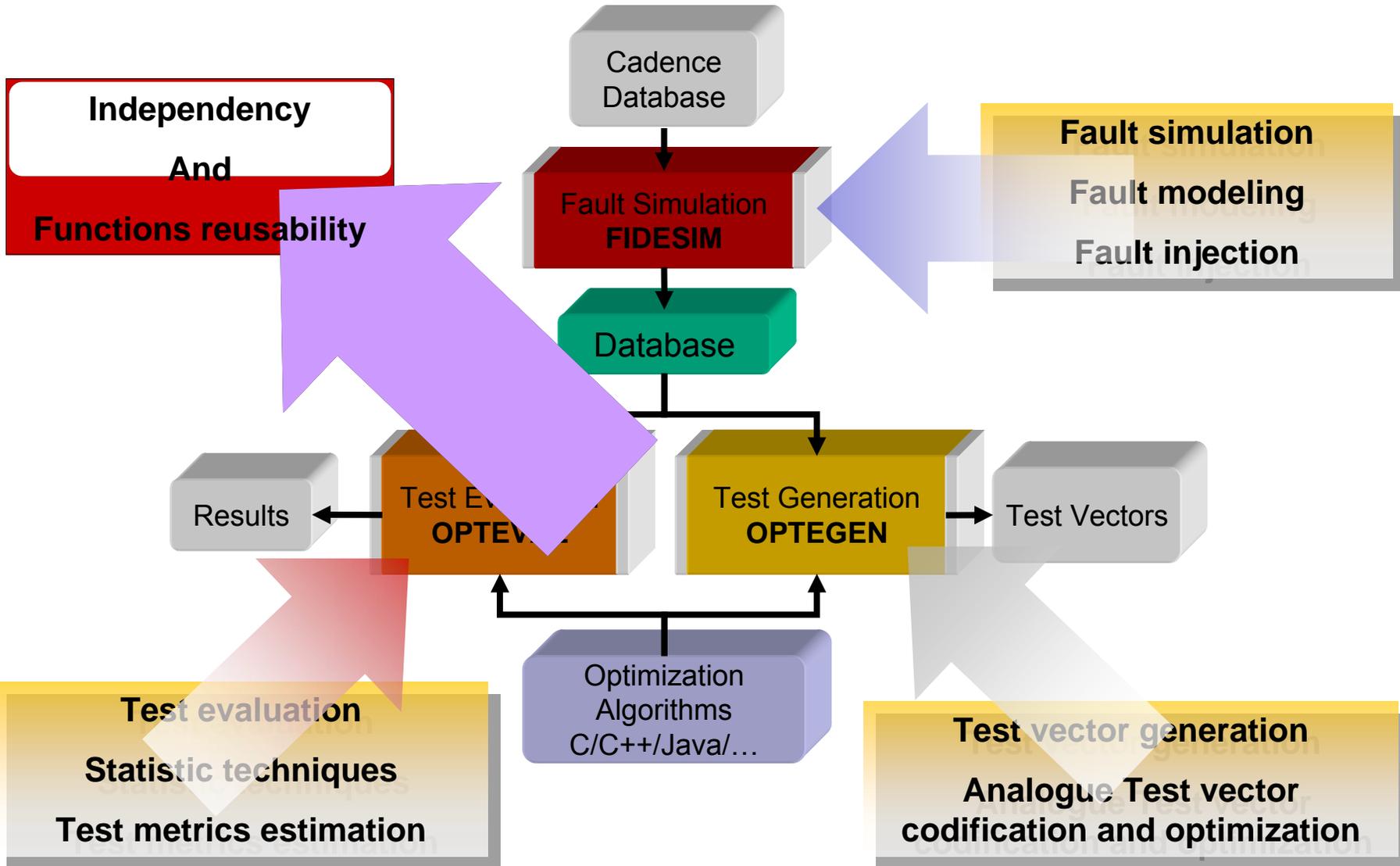
Estimation of the CUT impulse response

5 ***Computer-Aided Test (CAT)***

→ ***Computer aided testing :***

- ❑ Efficient design and test integration by using Computer-Aided Test (CAT) techniques
- ❑ Estimation of test metrics and setting of test limits
- ❑ Efficient determination of test patterns :
 - optimisation of functional tests
 - automatic generation of structural tests (ATPG)
- ❑ ATPG requires :
 - fault modelling techniques for analogue components
 - fault simulation of mixed-signal mixed-domain devices and calculation of fault coverage figures

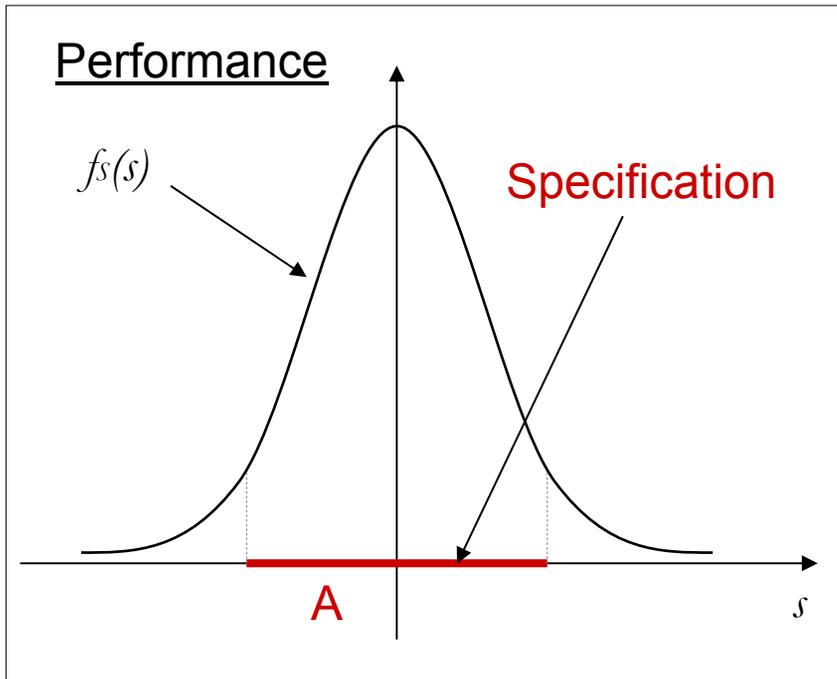
5 Computer-Aided Test (CAT)



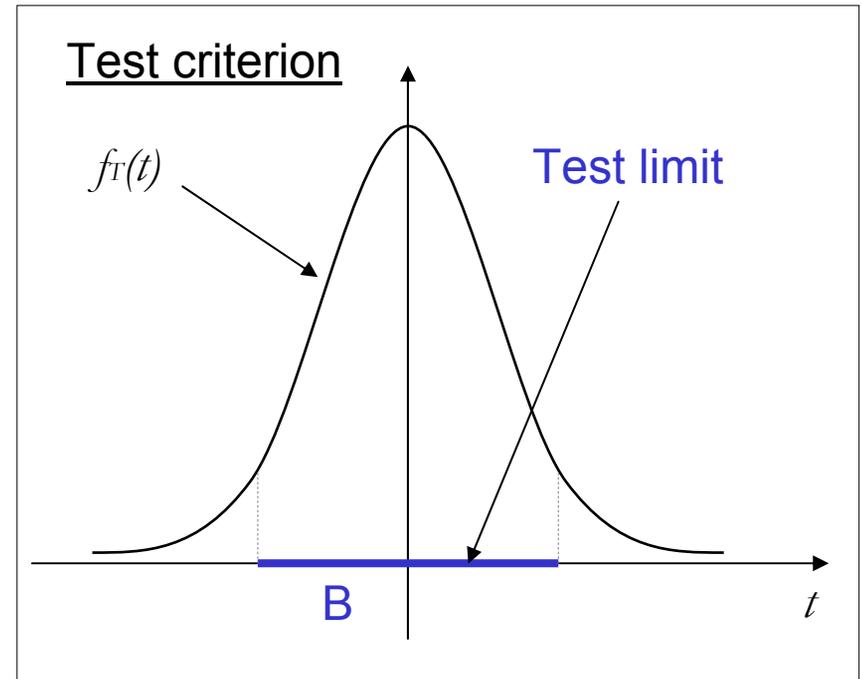
5 Computer-Aided Test (CAT)

→ Estimation of test metrics:

- It is necessary to work out the relationship between performances and test criteria.
- The metrics are used in order to set test limits.



$$P(\text{Functional}) = P(s \in A)$$
$$P(\text{Faulty}) = 1 - P(\text{Functional})$$
$$= 1 - P(s \in A)$$



$$P(\text{Pass}) = P(t \in B)$$
$$P(\text{Fail}) = 1 - P(\text{Pass})$$
$$= 1 - P(t \in B)$$

5 Computer-Aided Test (CAT)

→ Estimation of test metrics:

- Goal: find the joint Probability Density Function (PDF) between performances and test criteria

$$Y = P(\text{Functional})$$

$$Y = \int_{A_1} \dots \int_{A_n} f_S(s_1, \dots, s_n) ds_1 \dots ds_n$$

$$Y_T = P(\text{Pass})$$

$$Y_T = \int_{B_1} \dots \int_{B_m} f_T(t_1, \dots, t_m) dt_1 \dots dt_m$$

$$P_{PF} = \int_{A_1} \dots \int_{A_n} \int_{B_1} \dots \int_{B_m} f_{ST}(s_1, \dots, s_n, t_1, \dots, t_m) ds_1 \dots ds_n dt_1 \dots dt_m$$

$$Y_C = P(\text{Pass/Functional})$$

$$Y_C = \frac{P_{PF}}{Y}$$

$$D = P(\text{Faulty/Pass}) \\ = 1 - P(\text{Functional/Pass})$$

$$D = 1 - \frac{P_{PF}}{Y_T}$$

5 Computer-Aided Test (CAT)

→ Estimation of test metrics using a multi-normal PDF between performances and test criteria

Multinormal PDF

$$f(x) = \frac{1}{\sqrt{\det(2\pi\Sigma)}} \cdot \exp \left[-\frac{(x - \mu)^T \Sigma^{-1} (x - \mu)}{2} \right]$$

$$\Sigma = \begin{pmatrix} \sigma_1^2 & \cdots & \text{COV}(X_1, X_N) \\ \vdots & \ddots & \vdots \\ \text{COV}(X_N, X_1) & \cdots & \sigma_N^2 \end{pmatrix}$$

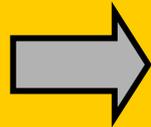
$$x = (x_1, x_2, \dots, x_N)$$

$$\mu = (\mu_1, \mu_2, \dots, \mu_N)$$

$$\text{COV}(X_1, X_2) = \frac{\sum_{i=1}^N X_1^i \cdot X_2^i}{N} - \mu_1 \mu_2$$

$$P(A) = \frac{1}{\sqrt{\det(2\pi\Sigma)}} \int_{A_1} \cdots \int_{A_p} \exp \left[-\frac{(x - \mu)^T \Sigma^{-1} (x - \mu)}{2} \right] dx_1 dx_2 \cdots dx_p$$

Run 1000
Monte Carlo
circuit
simulations



Calculate
multinormal PDF
parameters (μ and Σ)



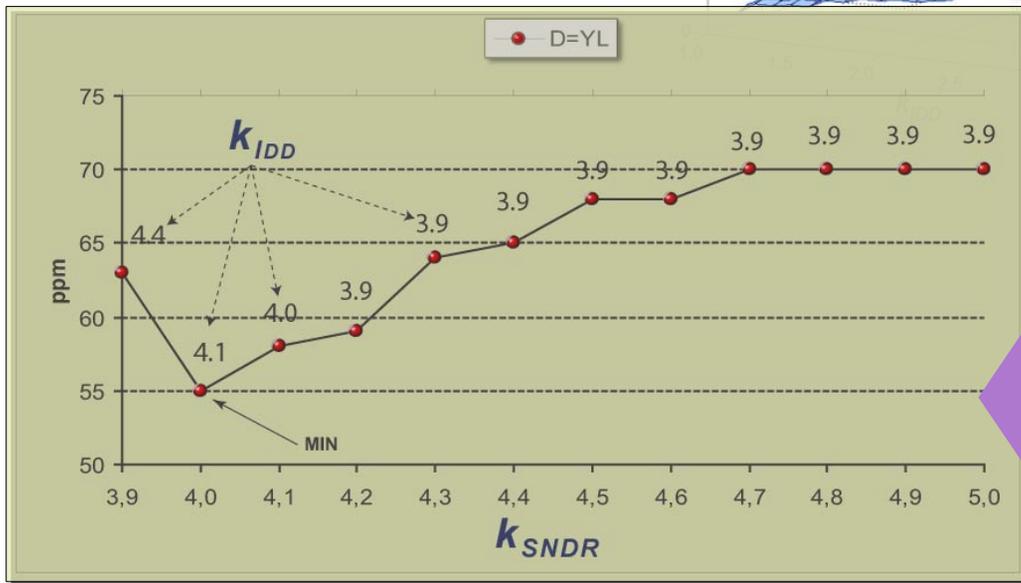
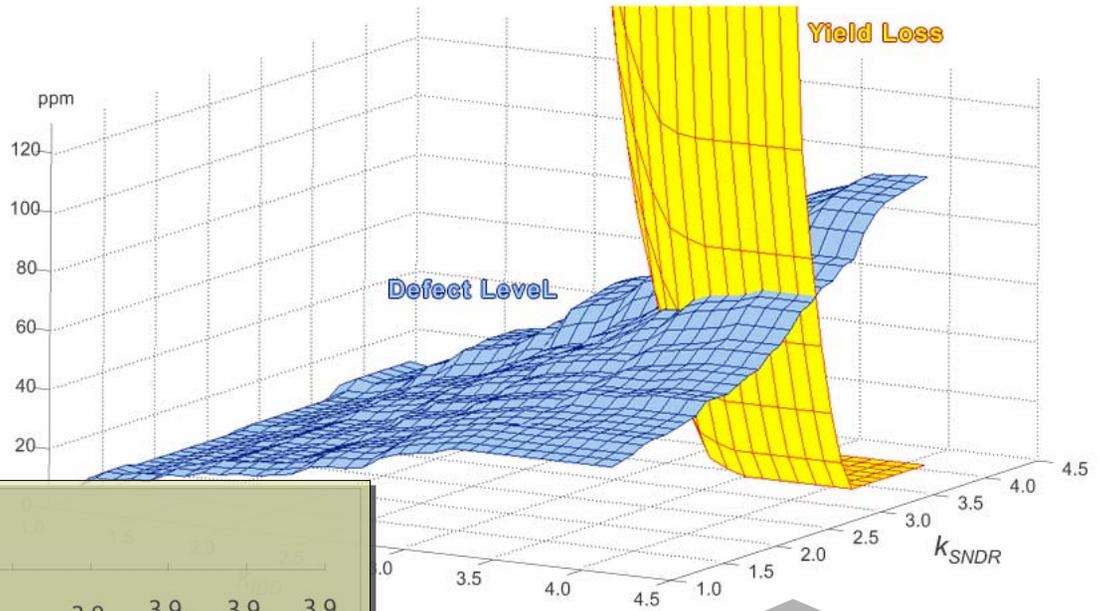
Generate millions of
circuit samples from the
multinormal law
(using Matlab, R, ...)

5 Computer-Aided Test (CAT)

→ Setting test limits as a function of test metrics:

SNDR
[$\mu - 4.0\sigma$, $\mu + 4.0\sigma$]

IDD
[$\mu - 4.1\sigma$, $\mu + 4.1\sigma$]



55 ppm

5 Computer-Aided Test (CAT)

- CADENCE-based CAT tool for the validation of test strategies

The image displays the Cadence Computer-Aided Test (CAT) tool interface, which is used for validating test strategies. The main window is titled "TEST EVALUATION 1" and "TEST EVALUATION 4". It features a menu bar with "Configuration", "Tools", and "About". The main area is divided into several panels:

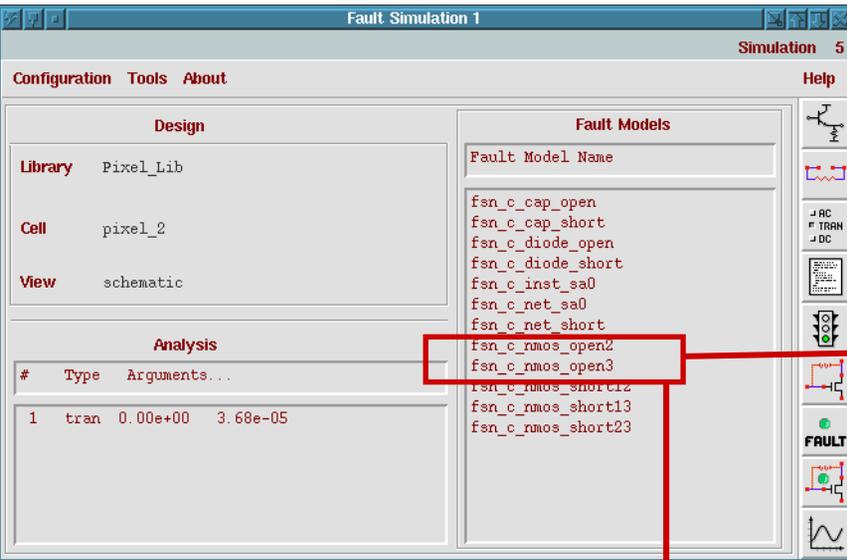
- Circuit Specifications:** This panel shows the configuration of test variables and tolerance ranges. It includes a table with columns for "Circuit Measures", "Specifications", and "Tolerance Range". The "Specifications" column contains expressions like $sp1 = \text{root}(tm1 \ 1.8 \ 2)$, $sp2 = \text{abs}((\text{value}(tm1 \ 20u) - \text{value}(tm1 \ 30u)) / 10u)$, and $sp3 = \text{math_lDistMax}(tm1 \ 20u \ 30u \ 1u \ 30)$. The "Tolerance Range" column shows values like $sp1: (0.1u, 37u)$, $sp2: (117000, 120320)$, and $sp3: (8.0e-3, 10.8e-3)$.
- Test Configuration:** This panel shows the configuration of test variables and tolerance ranges. It includes a table with columns for "Test Measures", "Test Variables", and "Tolerance Range". The "Test Variables" column contains expressions like $tv1 = \text{value}(tm1 \ 36.38u) - \text{value}(tm1 \ 36.28u)$. The "Tolerance Range" column shows values like $tv1: (0.5, 1.5)$.
- Test Configuration Program:** This panel shows the configuration of test variables and tolerance ranges. It includes a table with columns for "Test Measures", "Test Variables", and "Tolerance Range". The "Test Measures" column contains expressions like $tm1 = VT("/Sout")$. The "Test Variables" column contains expressions like $tv1 = \text{value}(tm1 \ 36.38u) - \text{value}(tm1 \ 36.28u)$, $sp1 = \text{root}(tm1 \ 1.8 \ 2)$, $sp2 = \text{abs}((\text{value}(tm1 \ 20u) - \text{value}(tm1 \ 30u)) / 10u)$, and $sp3 = \text{math_lDistMax}(tm1 \ 20u \ 30u \ 1u \ 30)$.

Blue arrows point from the text "CADENCE-based CAT tool for the validation of test strategies" to the "Circuit Specifications" and "Test Configuration" panels. The "Test Configuration Program" panel shows the generated test program code, including the following text:

```
TEST_THRESHOLD
tv1: (0.5, 1.5)
sp1: (0.1u, 37u)
sp2: (117000, 120320)
sp3: (8.0e-3, 10.8e-3)
TEST_MEASURES
tm1=VT("/Sout")
TEST_VARIABLES
tv1=value(tm1 36.38u)-value(tm1 36.28u)
sp1=root(tm1 1.8 2)
sp2=abs((value(tm1 20u)-value(tm1 30u))/10u)
sp3=math_lDistMax(tm1 20u 30u 1u 30)
```

Fault modelling, injection and simulation tool 25

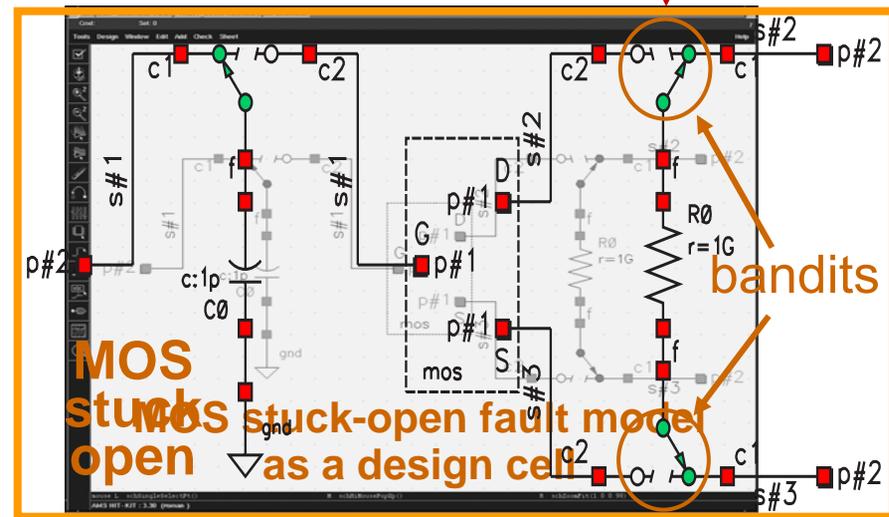
5 Computer-Aided Test (CAT)



```

/* Code sample for the fault model:
 * "MOS transistor stuck open" */
;# Design Under Test CellView
dsc_DUT=dbOpenCellViewByType("FAULT_DEMO"
    "THPixel" "schematic" nil "r")
;# Finding locations to inject faults
MOS=setof(X dsc_DUT->instances
    X->cellName=="nmos4" ||
    X->cellName=="pmos4")
;# List of all possible locations
LOC=dscGetInstSegsOnPins(MOS
    list("G" "D" "S"))
;# Specifying the current fault model
dsc_CURRENT_FAULT=list("FAULT_DEMO"
    "mosStuckOpen")
;# Building the fault scenario
LOCp1=dscLabelLocationsAs("concurrent" LOC)
LOCs=dscLabelLocationsAs("sequential"
    List(LOC LOCp1))
Dsc_FAULT_SCENARIO=dscBuildScenario(LOCs)

```

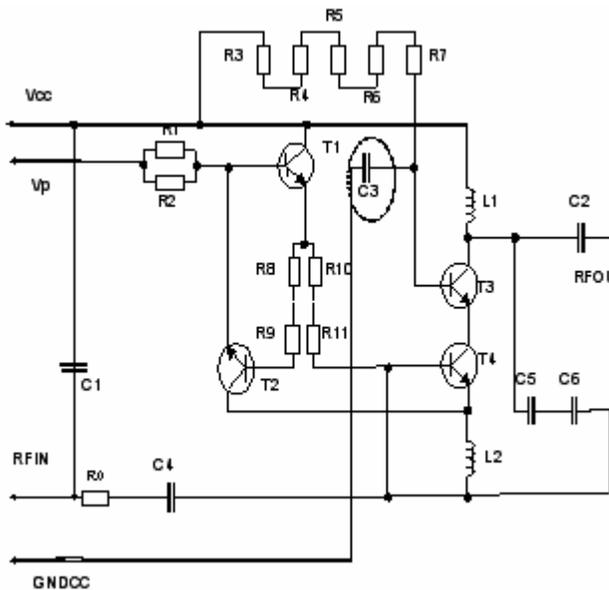


Fault modelling & fault injection

- Integrated in CADENCE

5 Computer-Aided Test (CAT)

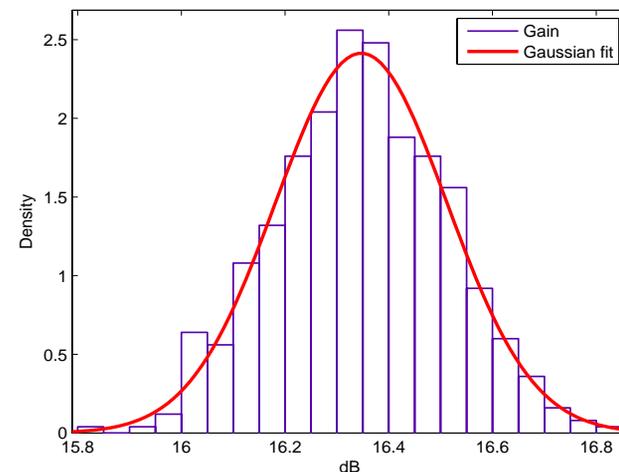
Test evaluation for an 0.25 μm BiCMOS
ST Microelectronics LNA amplifier



Performances @2.2GHz	μ	σ
NF (dB)	1.6	0.08
S_{11} (dB)	-12.4	0.46
S_{12} (dB)	-21.9	0.19
S_{21} (dB)	16.3	0.17
S_{22} (dB)	-15.5	1.28

Test measurements	μ	σ
I_{rms} (mA)	5.2	0.02
I_{pp} (mA)	3.6	0.14
V_{rms} (mV)	44.8	0.89
V_{pp} (mV)	129.3	2.29
I_0 (mA)	15.5	0.05
Z_1 (Ω) @2.2GHz	64.0	1.71
Z_2 (Ω) @2.2GHz	69.1	2.72

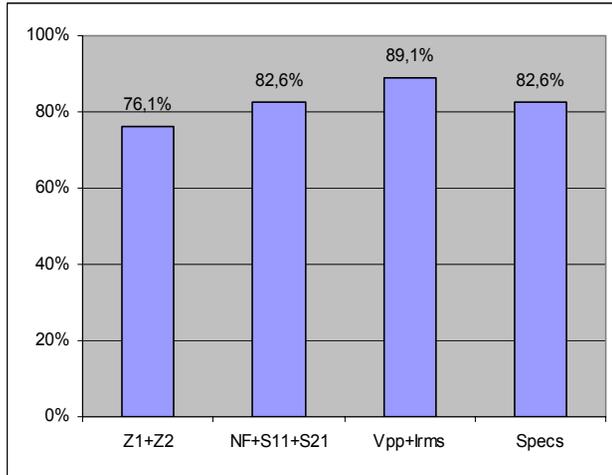
Test Limits	Min	Max
I_{rms} (mA)	5.1	5.3
I_{pp} (mA)	3.1	4.1
V_{rms} (mV)	41.6	48.0
V_{pp} (mV)	121.0	137.6
I_0 (mA)	15.3	15.7
Z_1 (Ω) @2.2GHz	57.9	70.1
Z_2 (Ω) @2.2GHz	59.4	78.8



LNA Gain Distribution
with Gaussian fitting

5 Computer-Aided Test (CAT)

Test evaluation for an LNA amplifier



Fault coverage evaluation for catastrophic faults considering performances (specs) and test measurements: LNA output voltage (V_{pp}) and current consumption (I_{rms}) achieve high fault coverage than circuit performances

Test N°	Test criteria	Defects	F	Y	YT	Yc	D
1	I_{rms}	1, 3, 6	9.2%	89.9%	99.0%	100%	9.2%
2	I_{pp}	None	0%	89.9%	100%	100%	10.0%
3	V_{rms}	1, 3, 6, 8, 9	58.7%	89.9%	92.1%	98.0%	4.3%
4	V_{pp}	1, 3, 6, 8, 9	60.6%	89.9%	88.9%	94.7%	4.1%
5	I_0	3, 6	12.8%	89.9%	98.6%	100%	8.8%
6	Z_1	1, 3, 6, 7, 8, 9	63.5%	89.9%	80.4%	86.0%	3.8%
7	Z_2	1, 3, 6, 7, 8, 9	16.9%	89.9%	94.4%	96.1%	8.4%
8	All test criteria	1, 3, 6, 7, 8, 9	64.2%	89.9%	77.3%	82.7%	3.7%

Fault coverage for most probable single parametric faults has been considered. Measuring of input impedance (Z_1) is necessary in addition to V_{pp} and I_{rms} to have at least partial coverage of all faults

6

Conclusions

- ❑ Test techniques for digital circuits (including DFT, BIST) are today well established.
- ❑ For analogue and mixed-signal circuits, much research is still required.
- ❑ The nature of analogue signals, the variety of analogue circuits and performances, the difficulty to provide fault models with wide acceptance, the difficulty to evaluate the quality of the tests, make mixed-signal testing a difficult topic.
- ❑ The basic analogue test approaches have been presented and DFT/BIST techniques introduced.
- ❑ Analogue testing techniques are largely multidisciplinary: techniques from signal processing, statistics, optimisation, machine learning, ... are required.